IN THE SPECIFICATION

At page 1 after the title and before the heading "Field of the Invention", add the following paragraph:

A1

-- This application is a divisional application of U.S. Application Serial Number 09/198,179 filed on November 23, 1998 now issued as U.S. 6,332,270, which is a divisional application of U.S. Application Serial Number 08/756,830 filed on November 20, 1996, which is a continuation of U.S. Application Serial Number 08/425,543 filed on April 20, 1995 now abandoned and is a continuation-in-part of U.S. Application Serial Number 09/921,867 filed on August 3, 2001, which is a continuation of U.S. Application Serial Number 08/872,519 filed on June 11, 1997 now issued as U.S. 6,334,247, which is a divisional of U.S. Application Serial Number 08/754,869 filed on November 22, 1996 now issued as U.S. 5,821,763, which is a continuation of U.S. Application Serial Number 08/055,485 filed on April 30, 1993 now issued as U.S. 5,635,846. --

Amend the paragraph bridging pages 6 and 7 as follows:

A2

-- Figure 1 shows a cross section of a test substrate (10) and high density integral rigid test probe (12) according to the present invention. The test substrate (10) provides a rigid base for attachment of the probe structures (12) and fan out wiring from the high density array of probe contacts to a larger grid of pins or other interconnection means to the equipment used to electrically test the integrated circuit device. The fan out substrate can be made from various materials and constructions including single and multi-layer ceramic with thick or thin film wiring, silicon wafer with thin film wiring, or epoxy glass laminate construction with high density copper wiring. The integral rigid test probes (12) are attached to the first surface (11) of the substrate (10). The probes are used to contact the solder balls (22) on the integrated circuit device (20). The solder balls (22) are attached to the first surface (21) of the integrated circuit device (20). Substrate (10) can include decoupling capacitor (2). --